

MATERIAL DECLARATION SHEET



Material Number	FWP227 Series			
Product Line	Fixed Resistors			
Compliance Date	2025/7/15			
RoHS Compliant	Yes	MSL	1	

Reference part number: FWP2274

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	20	Tin	7440-02-0	100	0.068	0.068
2	Leads	Copper	2400	Copper	7440-50-8	100	8.129	8.129
3	Inside Soldering	Tin Plating	510.57	Tin	7440-31-5	90.91	1.572	1.729
				Copper	7440-50-8	7.6	0.131	
				Silver	7440-22-4	1.49	0.026	
4	Heatsink	Copper Plate	16600	Copper	7429-90-5	100	56.224	56.224
5	Heatsink Plating	Nickel Plating	100	Nickel	7440-02-0	100	0.339	0.339
6	Chipbond	Filled Epoxy	200	Epoxy	25068-38-6	100	0.677	0.677
7	Nuts	Stainless Steel	2800	Chromium	7440-47-3	17	9.484	9.484
				Iron	7439-89-6	68		
				Nickel	7440-02-0	12		
				Molybdenum	7439-98-7	3		
8	Foibond	Foibon	20	Dimethylacetamide	127-19-5	100	0.068	0.068

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8	Resistor Material	Manganin ^{R1}	300	Copper	7440-50-8	83	0.843	1.015
				Nickel	7440-02-0	3	0.03	
				Manganese	7439-96-5	14	0.142	
9	Cover	Silicone Based	10	Silicon	7440-21-3	100	0.034	0.034
10	Substrate	Ceramic	930	Alumina	1344-28-1	99.59	3.137	3.15
				Silicon Dioxide	7631-86-9	0.41	0.013	
11	Solder Resist	Epoxy	2400	Epoxy	68928-70-1	100	0.339	0.339
12	Body T227	Epoxy	4630.5	Epoxy Black	68928-70-1	100	15.684	15.684
13	Body Bond	Epoxy	2625	Epoxy	68928-70-1	100	0.889	0.889
14	Body Filling	Epoxy	6410	Epoxy	68928-70-1	100	2.171	2.171
			Total weight	39956.07				

This Document was updated on: 2025/7/15

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size